

Case No.: AMKOR-017A
Patent Appln.

#813
BEO
2-4-03



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|-------------|-----------------------|---|----------------------------|
| Applicant: | Jong Sik Paek ✓ |) | |
| | |) | Group No.: 2812 |
| Serial No.: | 10/043,946 ✓ |) | |
| | |) | Examiner: Simkovic, Viktor |
| Filed: | 01/11/2002 ✓✓ |) | |
| | |) | |
| For: | SEMICONDUCTOR PACKAGE |) | |
| | WITH STACKED DIES |) | |

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON D C 20231

Dear Sir/Madam:

In response to the Office Action mailed October 24, 2002, in relation to the above identified patent application, please amend the application as follows:

In the Claims:

Please amend the following claims:

- 54601
B1
3. (Amended) The semiconductor package of Claim 1 wherein:
- the conductive connectors comprise first and second conductive wires;
 - the bond pads of the first semiconductor die are electrically connected to respective ones of the first surfaces of the leads by the first conductive wires; and
 - the bond pads of the second semiconductor die are electrically connected to respective ones of the second surfaces of the leads by the second conductive wires.

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